STANFORD UNIVERSITY - SCHOOL OF ENGINEERING

US-ASIA TECHNOLOGY MANAGEMENT CENTER

EE-402S Topics in International Advanced Technology Research

Theme: Advanced Electronics and IT for Energy Applications

The Occam Process:

An Energy Efficient Approach to Electronic Assembly, Interconnection and Data Transmission Management

Reducing the energy required in manufacturing, packaging, and system assembly is of critical concern to the chip industry. The Occam Process is one approach that bypasses soldering processes. Tested components are (1) positioned and bonded on temporary substrate carriers, (2) encapsulated, and (3) removed from the substrate to expose terminations. Then, the terminations are interconnected,e.g. by copper plating.

A 38 year electronics interconnection industry veteran, author, and serial entrepreneur, Mr. Joseph Fjelstad has more than 225 issued or pending U.S. and international patents.

Joseph Fjelstad

CEO

Verdant Electronics

Thursday, April 16th 4:15 - 5:30 PM

Skilling Auditorium, Stanford

Visitors Welcome • Light Refreshments

Details: http://asia.stanford.edu/

Students register for EE-402S (no prerequisites)

Contact: skeda at stanford dot edu

Phone: 650-724-0096